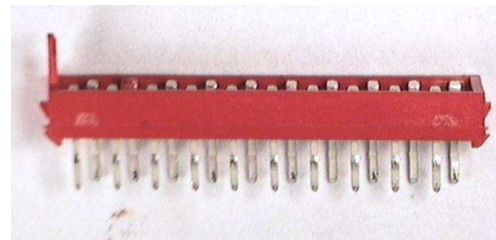
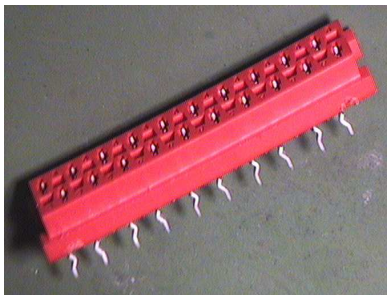


Job Number E04.07.01	Project Number: 770002	Date of issue: May 2005
Description: MicroMatch Resistance to lead-free wave soldering heat		Part numbers: 9-215079-0 rev. S (Female on board) 2-215464-0 rev. L (Male on board)

Scope:

To verify resistance to soldering heat for lead-free wave soldering.

**Conclusions:**

No detrimental effects or visual aspects were found after exposure to soldering heat at 265 °C for 10 seconds.

Note: this report is valid for all wave soldered Micro Match products.

Test Specification:	Product Specification 108-19052 Rev. E. Tyco Test-Spec. 109-202, Rev. B	
Test Carried Out:	1 Exposure to soldering heat 2 Visual inspection 3	
Distribution:	1 R. Verbeet 2 Doc. center 3 File Lab.	
Test Engineer: H. van Oosterhout	Requested by: R. Verbeet	
Laboratory Manager: D.M.J. Jooren.	Classification: Unrestricted	
Disposal of Samples: Destroyed	Report Number: 501-19093 Rev. O	
Appendices:	Page 1 of 2 Pages	

SAMPLE DESCRIPTION

10 Female on board connectors,
10 Male on board connectors.

TEST PROCEDURES

Tyco 109-202,
§4 Method B

RESISTANCE TO SOLDERING HEAT

Solder tails of the connectors were manually dipped in molten solder at a temperature of 265°C during 10 seconds. The test was performed with and without a printed circuit board.

IEC 60512-1-1:
Test 1a

VISUAL EXAMINATION

The test samples were visually inspected under a stereomicroscope, at a 10x magnification, with suitable illumination.

EQUIPMENT USED

Tensile tester	MTS	400M	165811-20	10-04
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TESTRESULTS

Visual inspection: No detrimental effects were found.